

|   | Type | L # | Hits   | Search Text   | DBs                                   | Time Stamp          |
|---|------|-----|--------|---|---------------------------------------|---------------------|
| 1 | BRS  | L1  | 71     | hous\$4 and packag\$3 and die<br>and grid near array and<br>side near1 wall\$ and<br>circuit  | USPAT;<br>EPO;<br>JPO;<br>DERWEN<br>T | 2003/02/23<br>22:17 |
| 2 | BRS  | L2  | 53     | ( "3337838"   "3366915"  <br>"3444506"   "3676748"  <br>"3676993"   "4167647"  <br>"4331831"   "4423468"  <br>"4437718"   "4487463"  <br>"4572604"   "4616406"  <br>"4655526"   "4660069"  <br>"4675472"   "4698663"  <br>"4705917"   "4734042"  <br>"4766479"   "4897055"  <br>"4931908"   "4943846"  <br>"4975066"   "4989318"  <br>"4997376"   "5008734"  <br>"5022144"   "5037311"  <br>"5049974"   "5071363"  <br>"5081563"   "5091772"  <br>"5123164"   "5137456"  <br>"5138438"   "5182853"  <br>"5220491"   "5281151"  <br>"5283717"   "5285104"  <br>"5309024"   "5326936"  <br>"5327325"   "5334279"  <br>"5342999"   "5347429"  <br>"5351393"   "5371404"  <br>"5376825"   "5390412"  <br>"5403784"   "5428505"  <br>"5438224") .PN. | USPAT                                 | 2003/02/23<br>22:11 |
| 3 | BRS  | L3  | 0      | pack\$3 and sie near wall\$<br>and lead\$ and semiconductor   | USPAT;<br>EPO;<br>JPO;<br>DERWEN<br>T | 2003/02/23<br>22:30 |
| 4 | BRS  | L4  | 139328 | semiconductor and pack\$3<br>and side near wal(die or<br>chip) and plate  | USPAT;<br>EPO;<br>JPO;<br>DERWEN<br>T | 2003/02/23<br>22:31 |
|   |      |     |        | semiconductor and pack\$3   | USPAT;<br>EPO;                        |                     |

|   | Type | L # | Hits | Search Text                               | DBs                                   | Time Stamp          |
|---|------|-----|------|---|---------------------------------------|---------------------|
| 6 | BRS  | L6  | 1329 | 4 and insulat\$3 same side<br>near wall\$ | USPAT;<br>EPO;<br>JPO;<br>DERWEN<br>T | 2003/02/23<br>22:37 |